

CORRELATIVE NANOMECHANICAL MEASUREMENTS

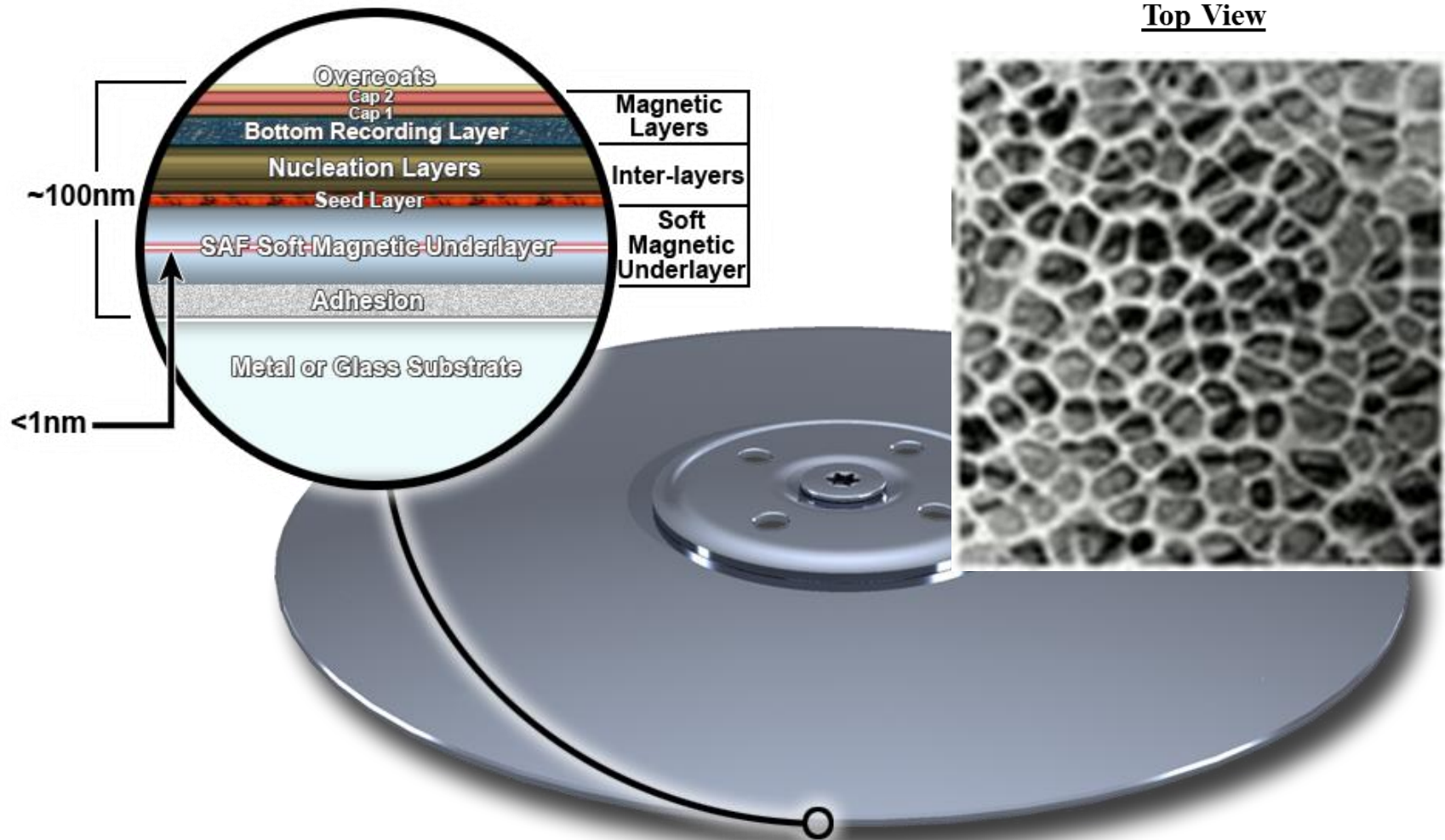
Douglas Stauffer, E. Hintsala, S.A.S. Asif
Hysitron, Inc.

Daniel Bufford, William Mook, Khalid Hattar
Sandia National Laboratories

CORRELATIVE NANOMECHANICAL MEASUREMENTS FOR COMPLEX ENGINEERED SYSTEMS

Anonymous Collaborators!!!

Complex, Engineered, System



I. Understanding damage mechanisms

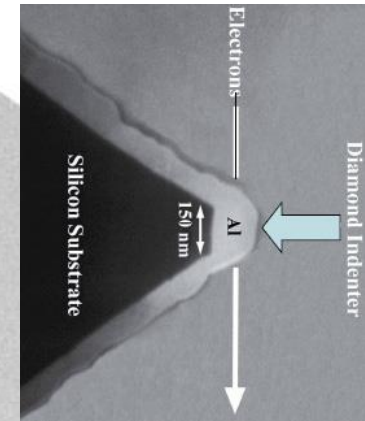
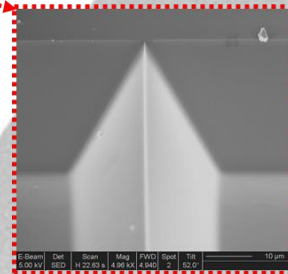
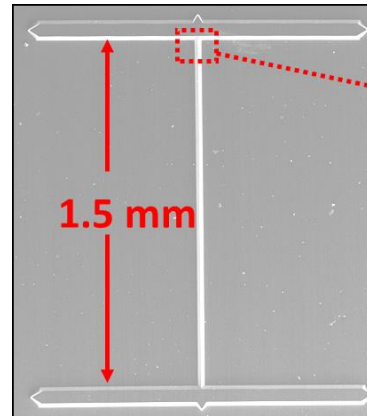
1. Co-deposited films for a direct comparison
between *in* and *ex situ* mechanical testing
2. Indentation to look at controlled stress-field statistics
 - Hardness and modulus as a function of depth/strain
3. *In Situ* TEM testing to look at deformation mechanisms
4. *In Situ* TEM scratch testing
 - – moving towards realism in measurements

Film Deposition

TEM PicoIndenter®



PI 95

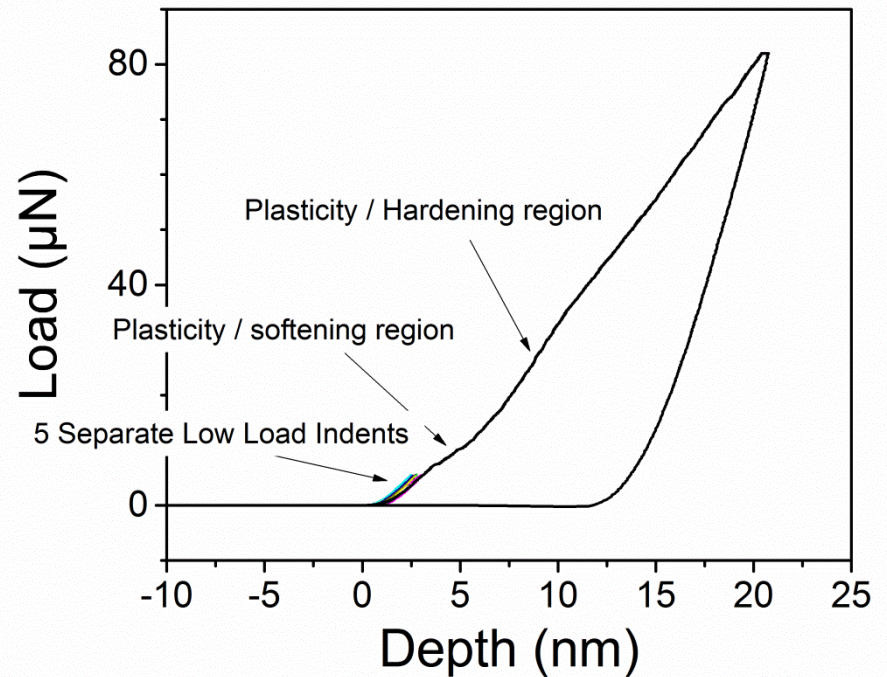
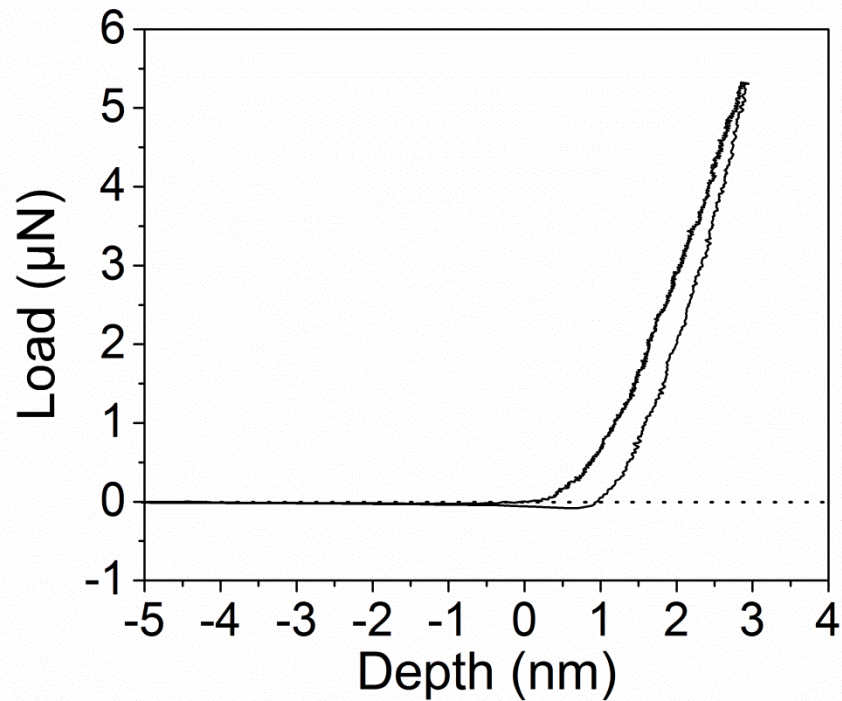


Film Stack

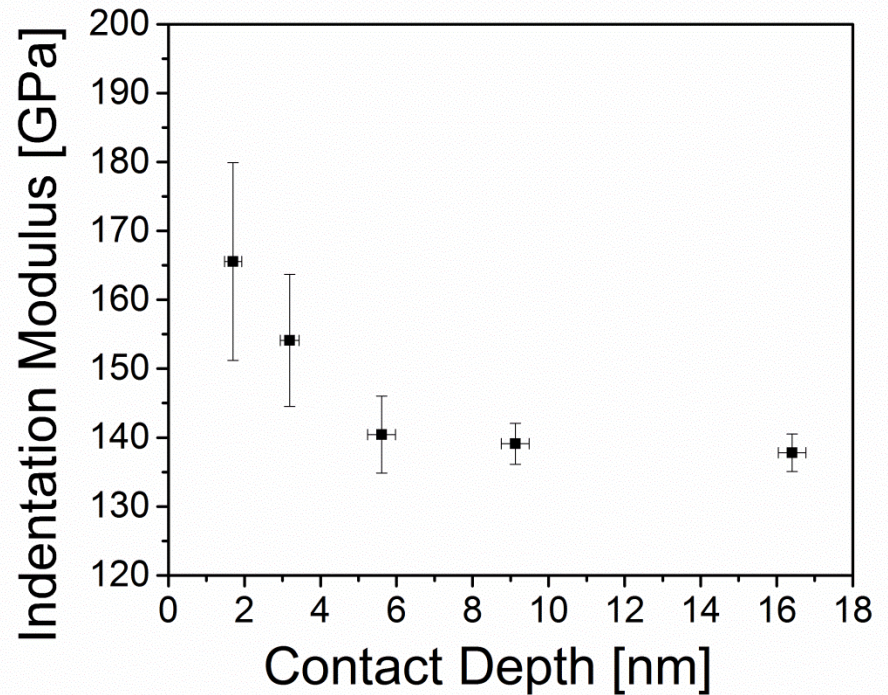
Carbon Overcoat
Perpendicular Pt-X magnet
Magnetic orientation layer
Seed layers

Silicon Wedge Substrate

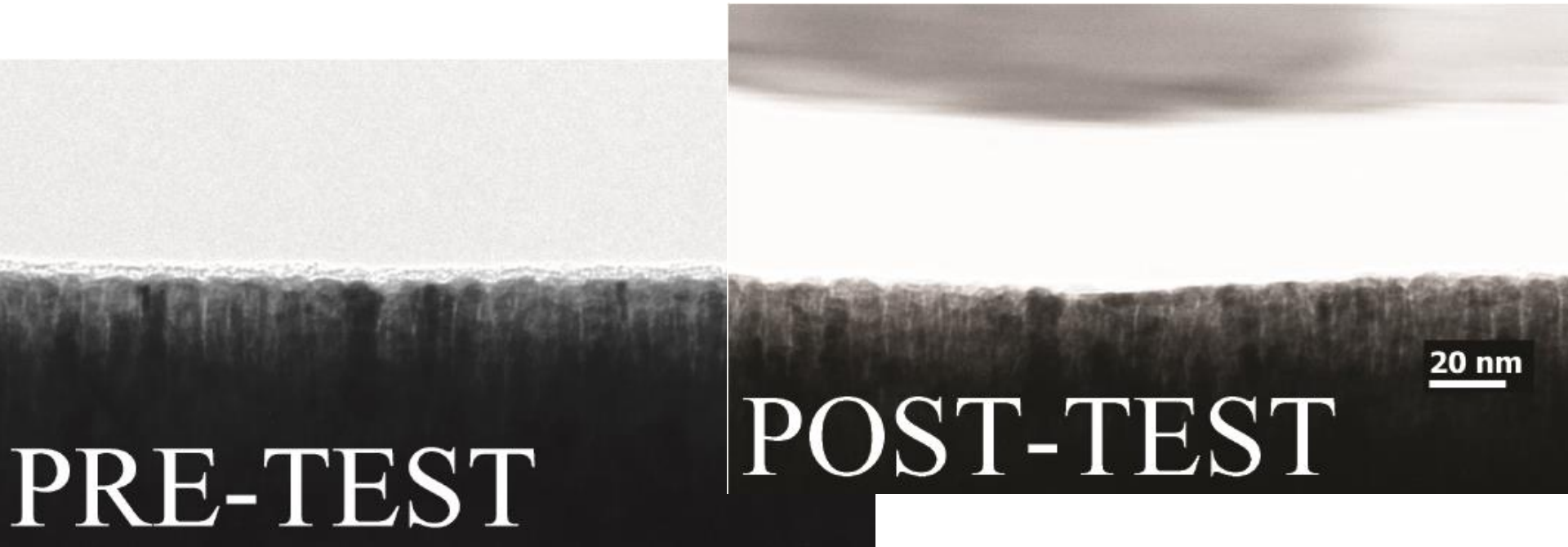
Indentation



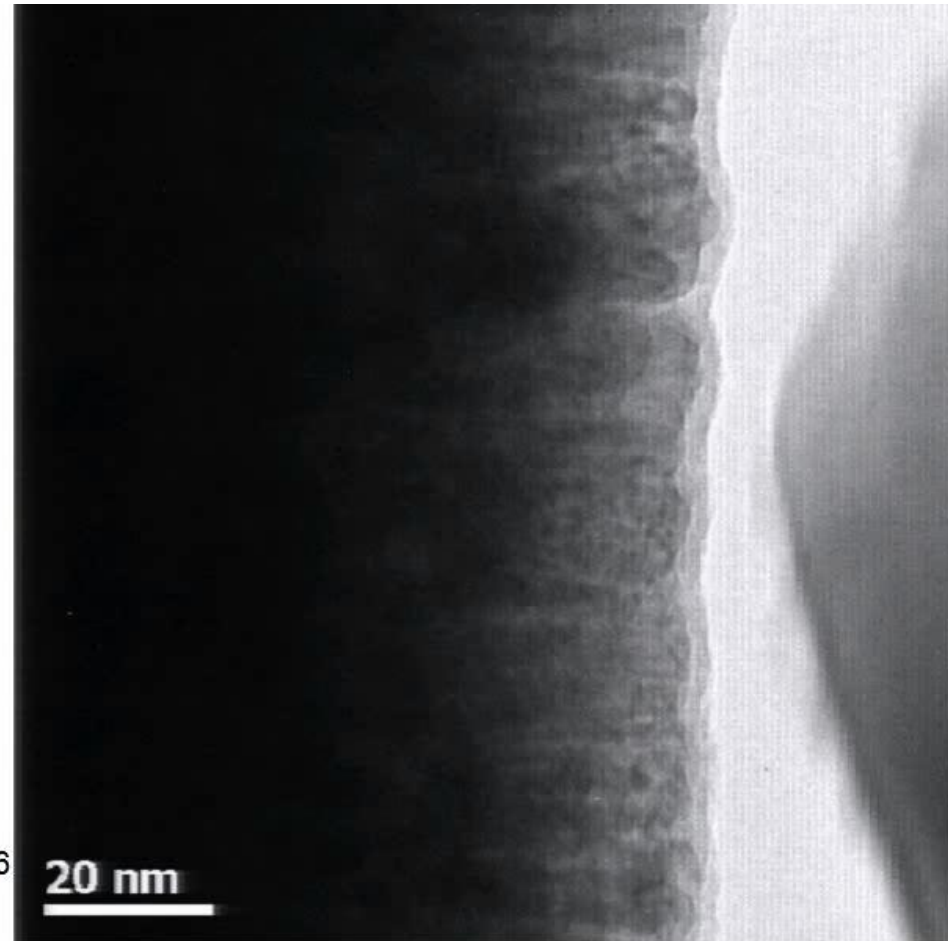
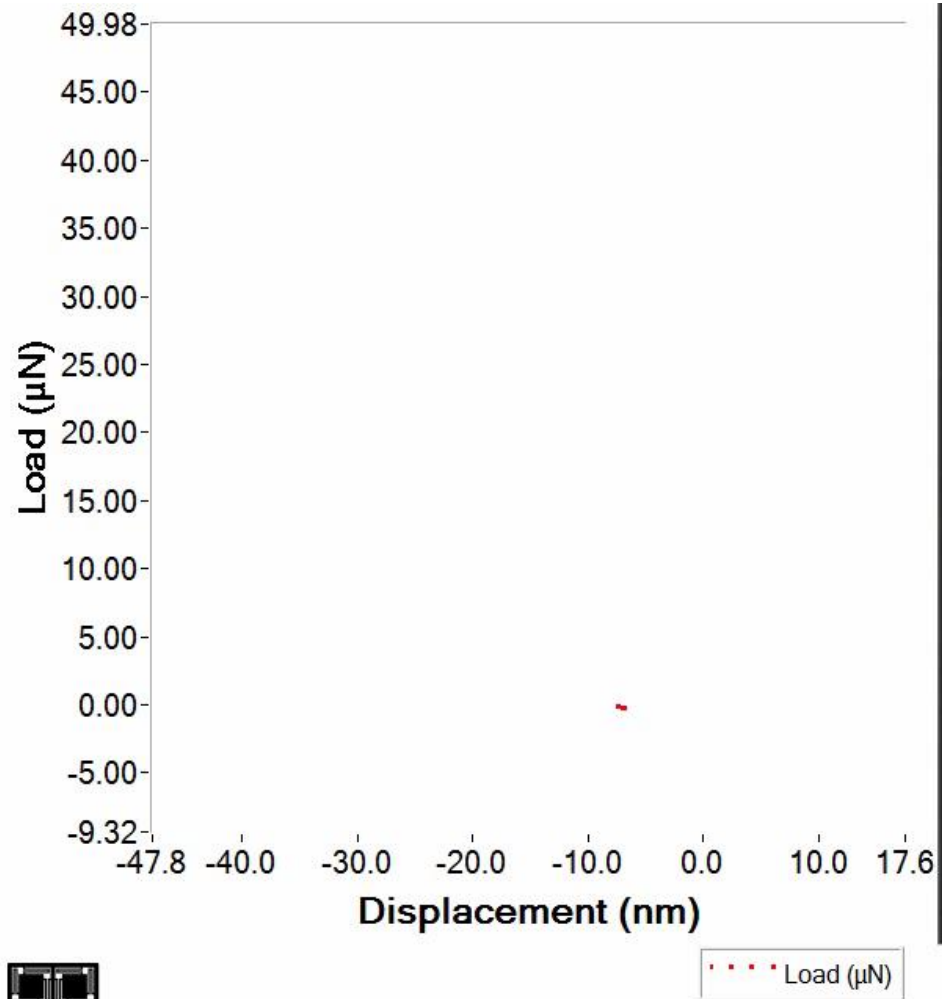
Douglas Stauffer



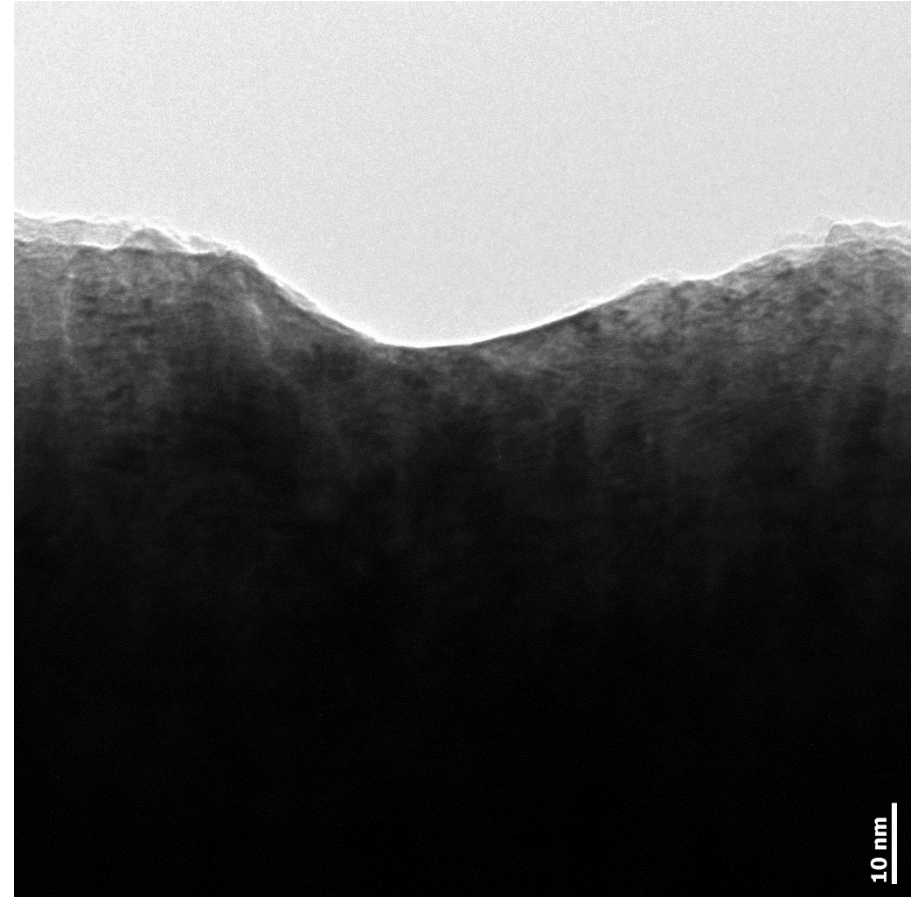
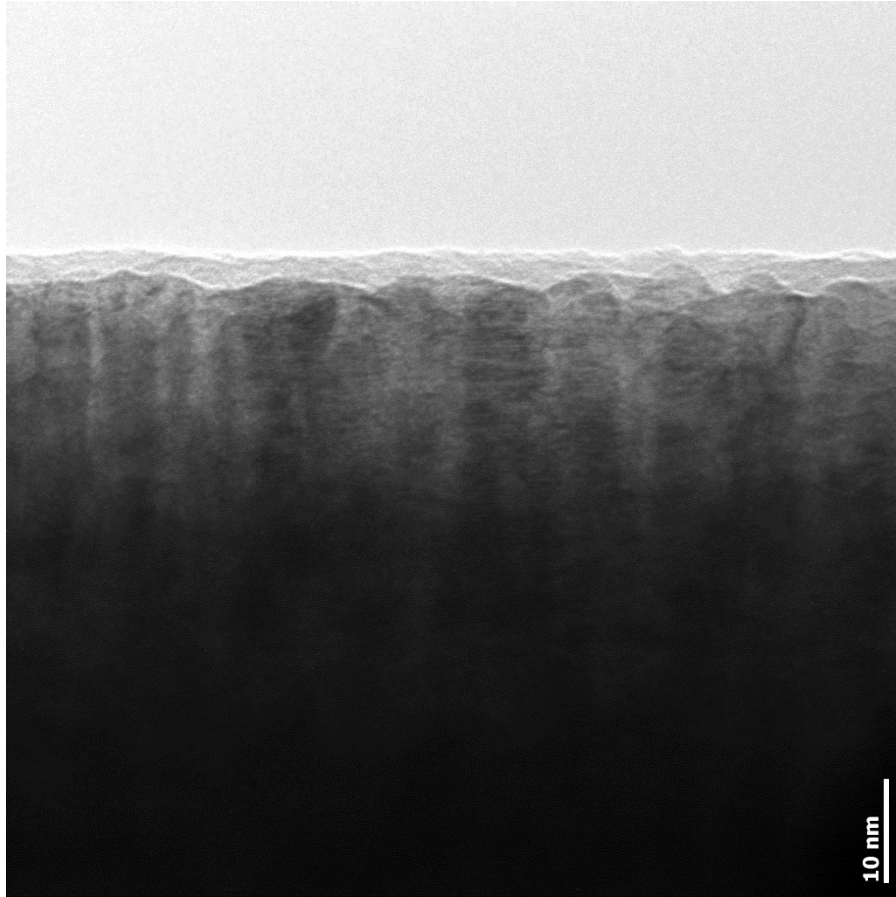
In Situ – Low Load



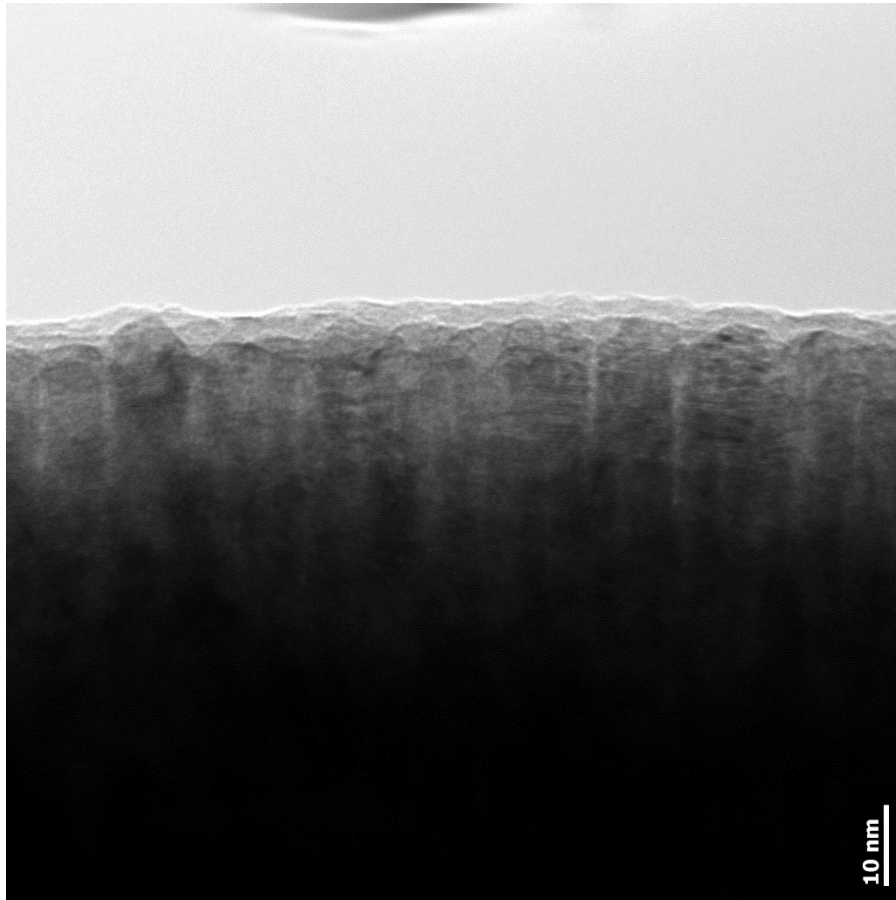
In Situ – Increasing Load



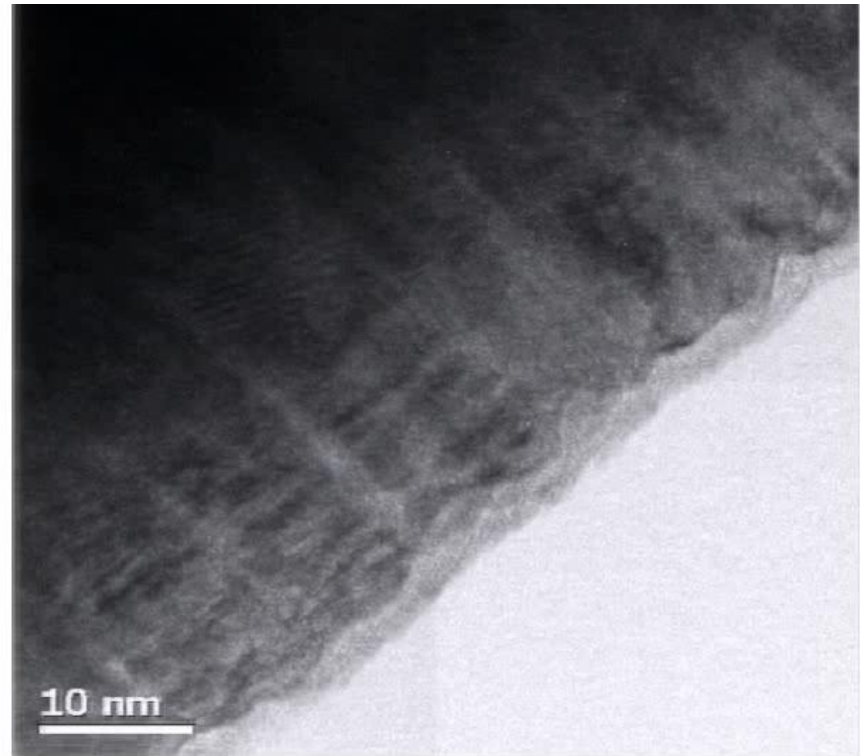
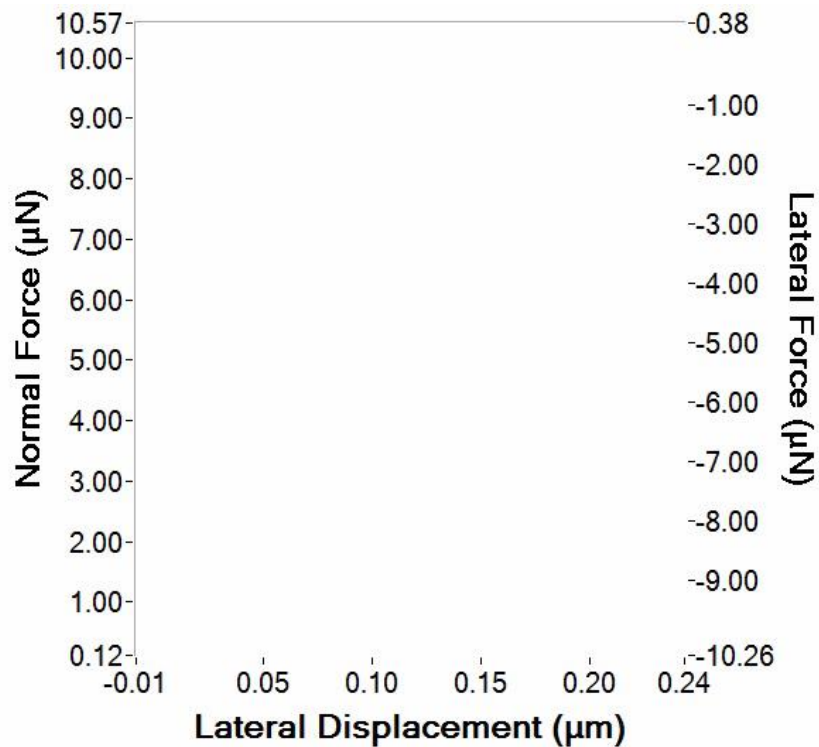
In Situ – Increasing Load



In Situ – Increasing Load



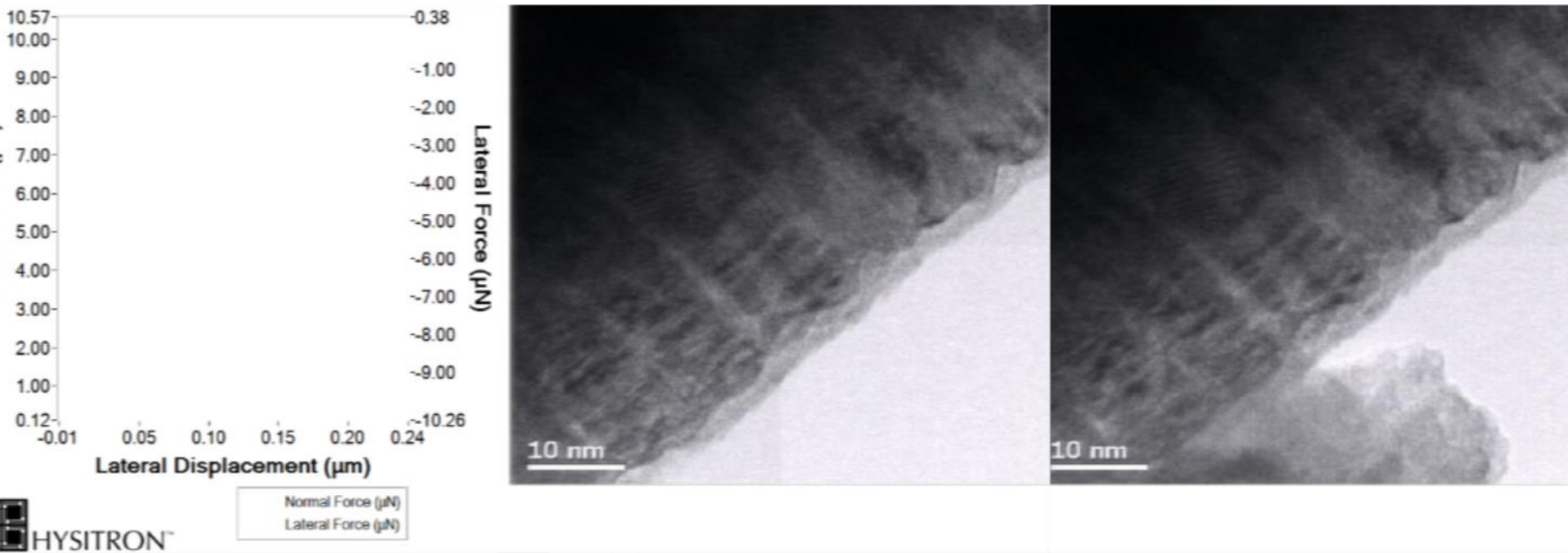
In Situ – Scratch



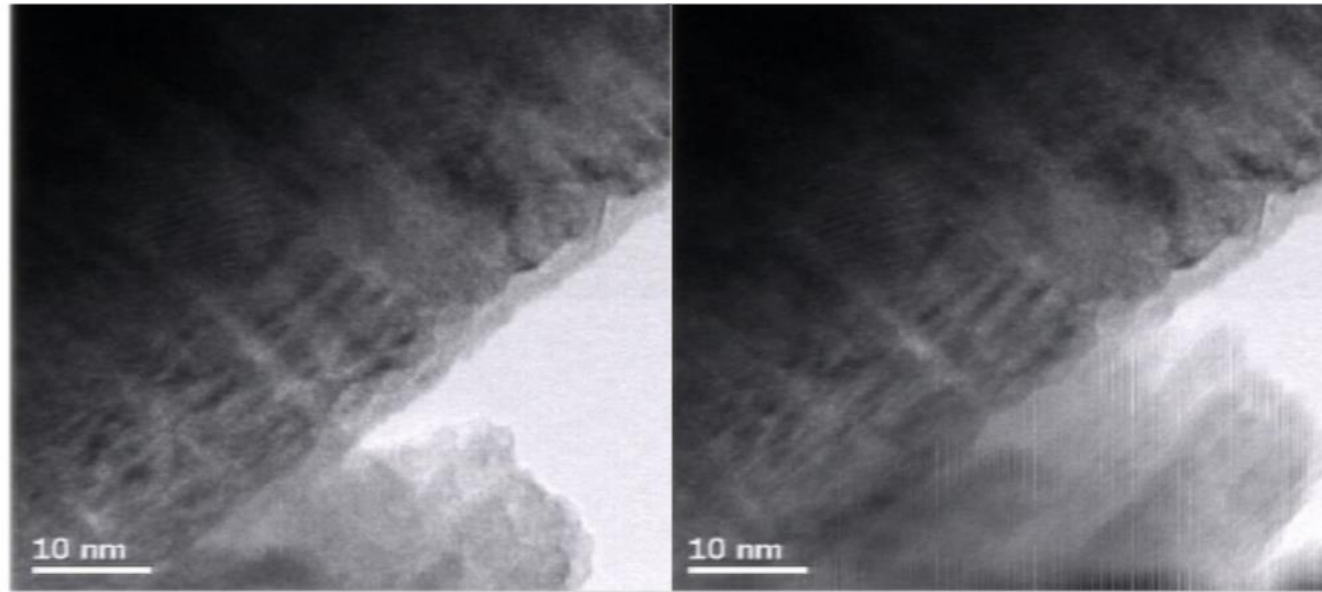
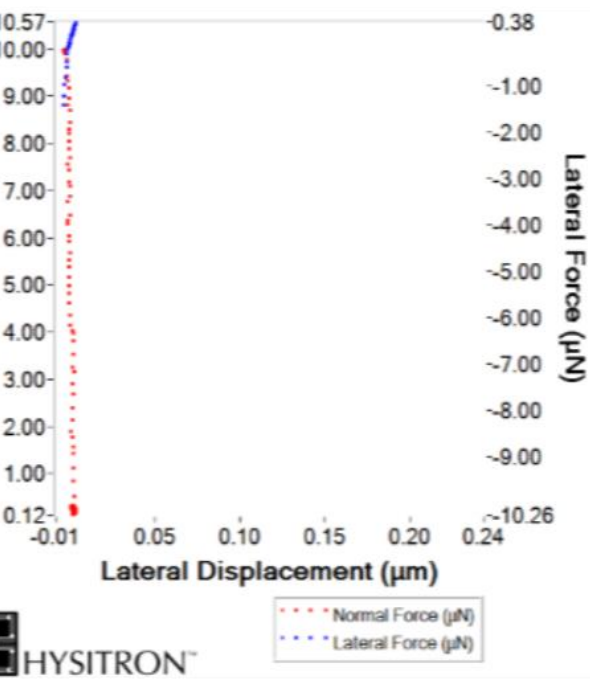
Normal Force (μN)
Lateral Force (μN)



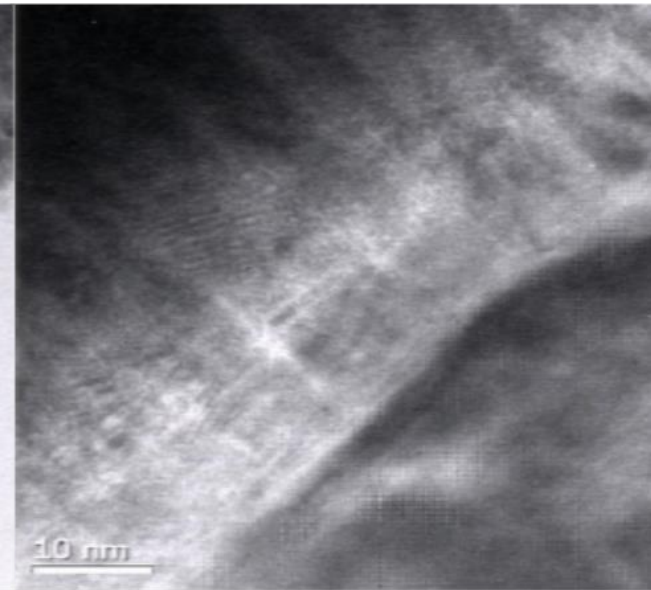
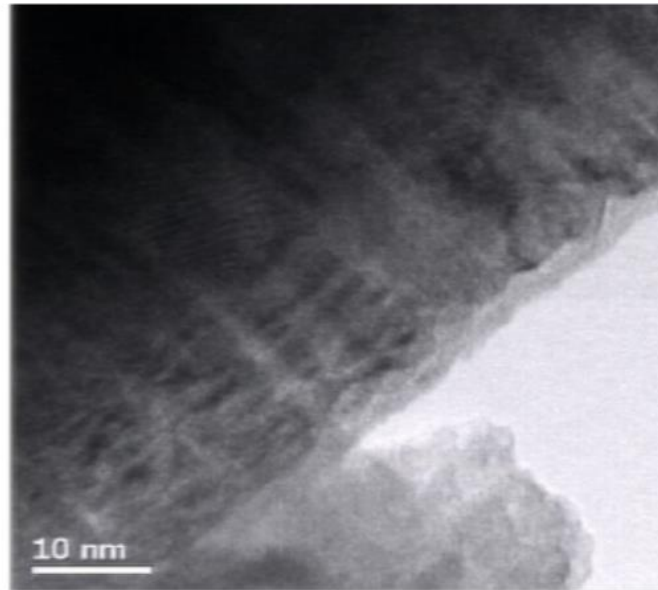
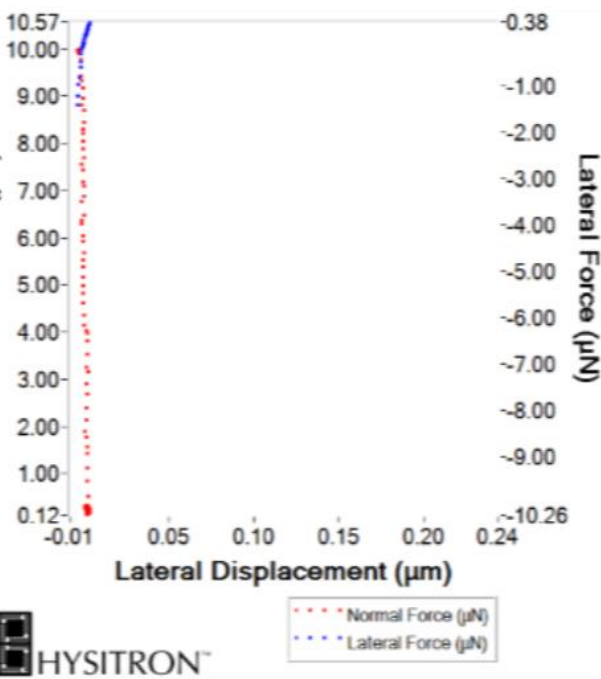
Tribology - Grain Rotation



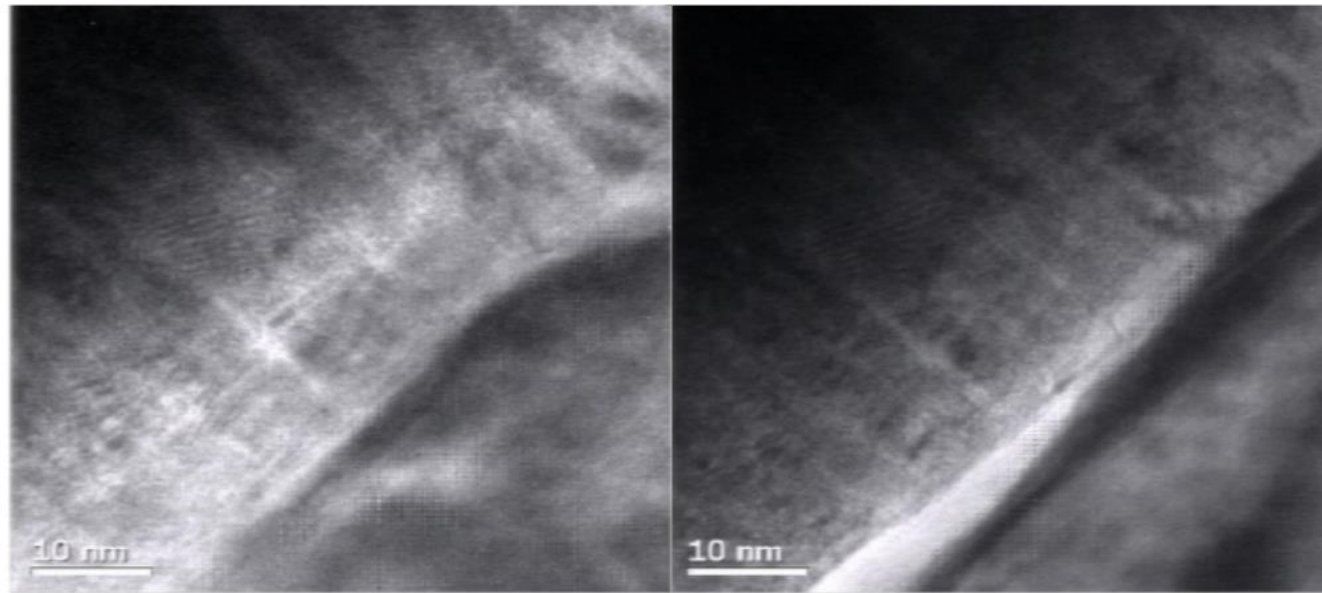
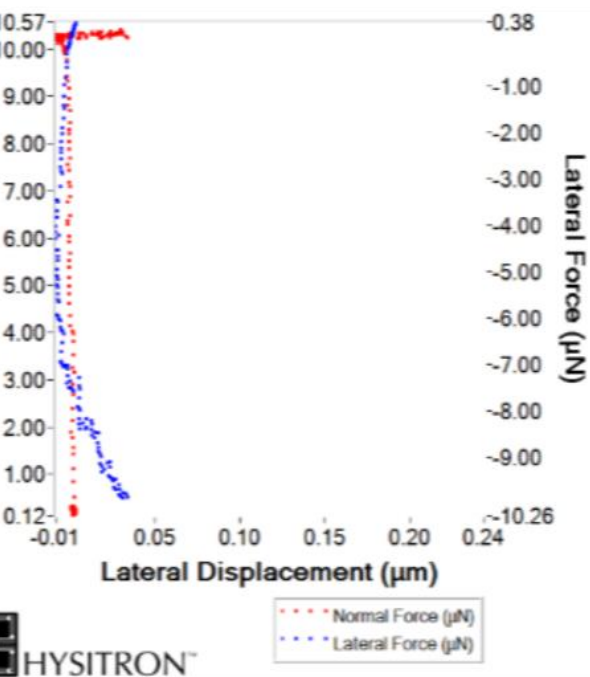
Tribology - Grain Rotation



Tribology - Grain Rotation

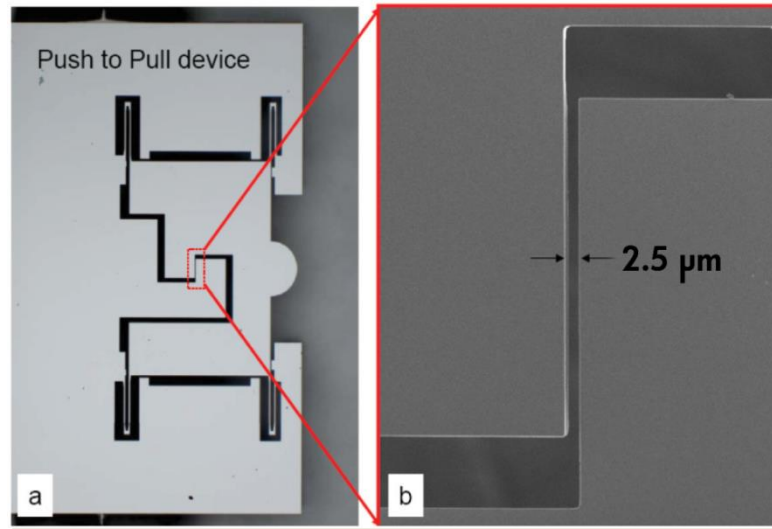
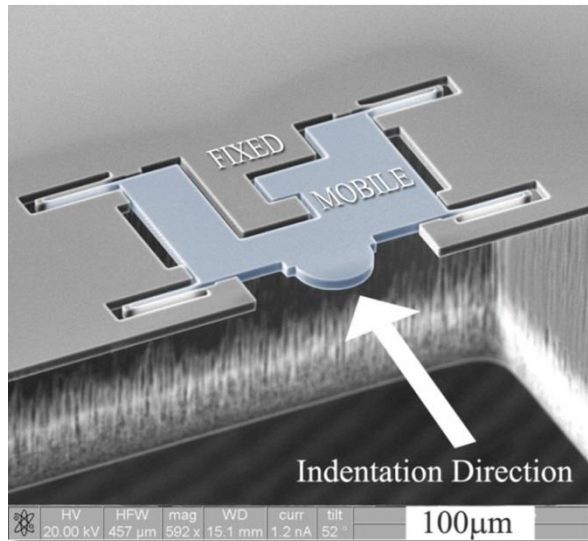


Tribology - Grain Rotation

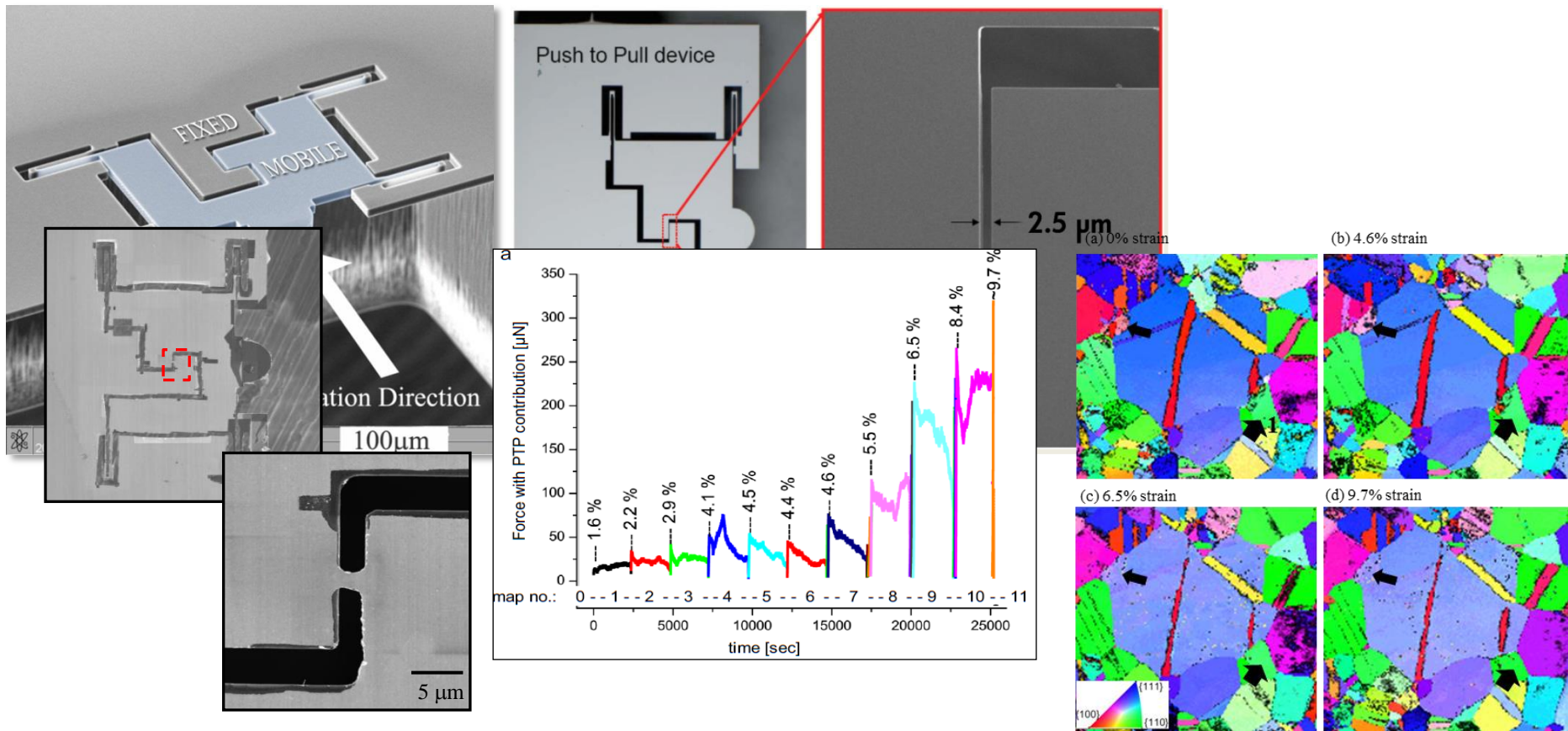


I. Fatigue in Cu thin films

In Situ TEM Tensile Testing



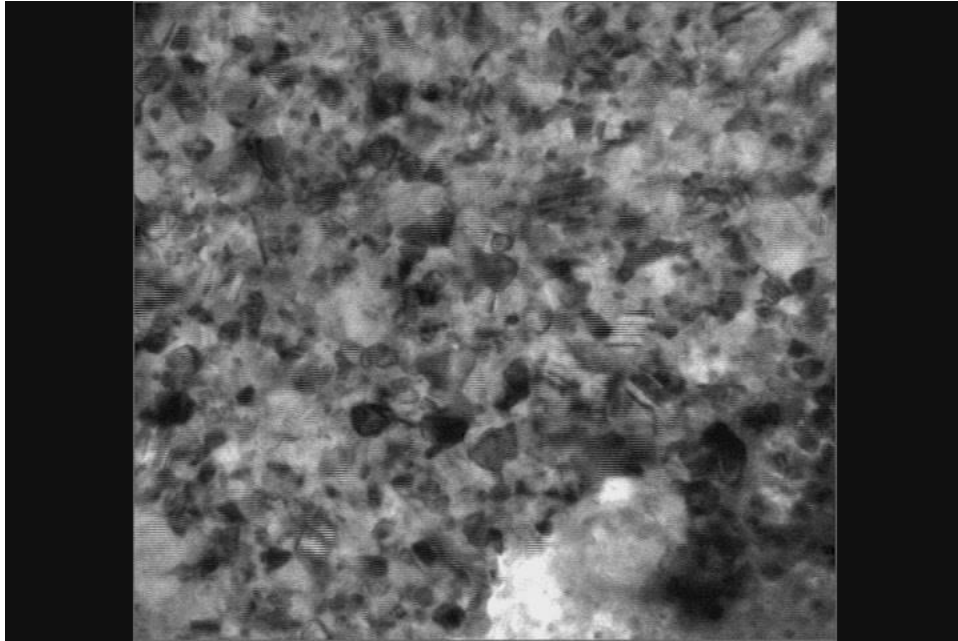
In Situ TEM Tensile Testing



Courtesy Christian Kübel, Karlsruhe Institute of Technology / Karlsruhe Nano Micro Facility

Combination of *in situ* straining and ACOM TEM: a novel method for analysis of plastic deformation of nanocrystalline metals, A. Kobler, A. Kashiwar, H. Hahn, C. Kübel, *Ultramicroscopy*, 128, 68-81 (2013); DOI: 10.1016/j.ultramicro.2012.12.019

Crack Initiation



Pull in tension to $150\mu\text{N}$

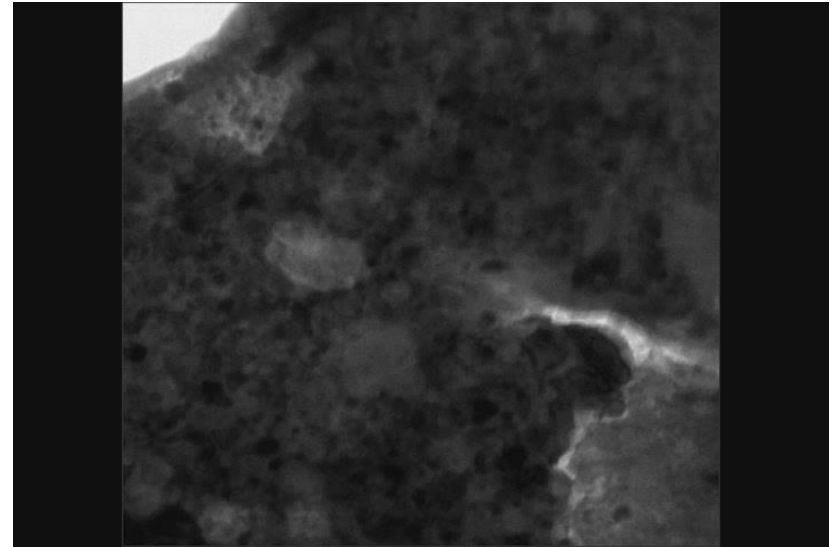
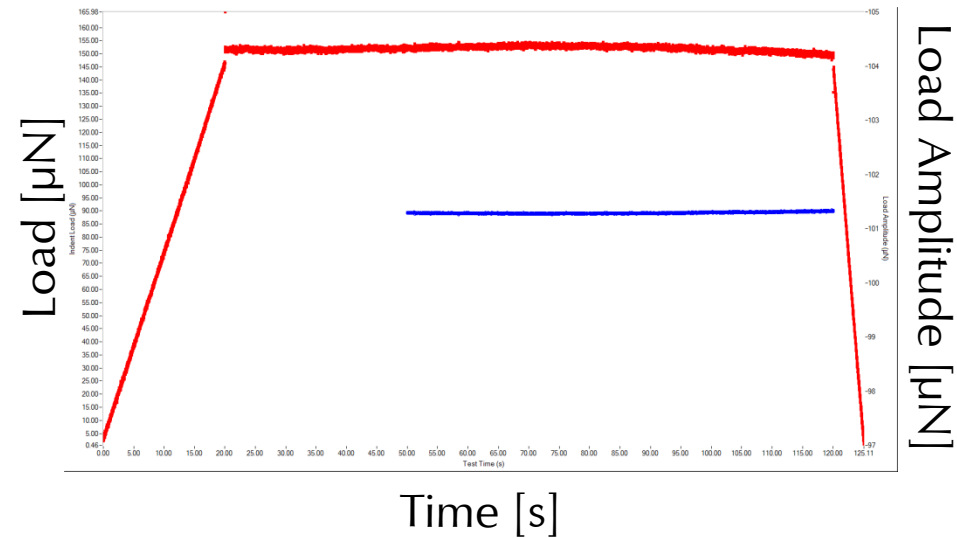
Cycle at 1 Hz

$$R = 0.5 = \frac{P_{min}/A}{P_{max}/A} = \frac{100\mu\text{N}}{200\mu\text{N}}$$

Crack Growth

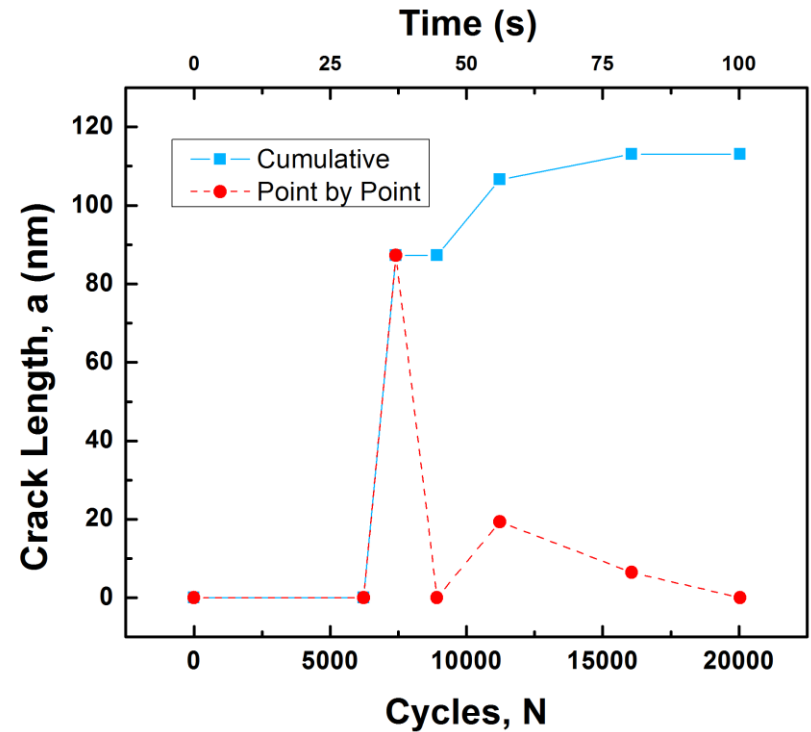
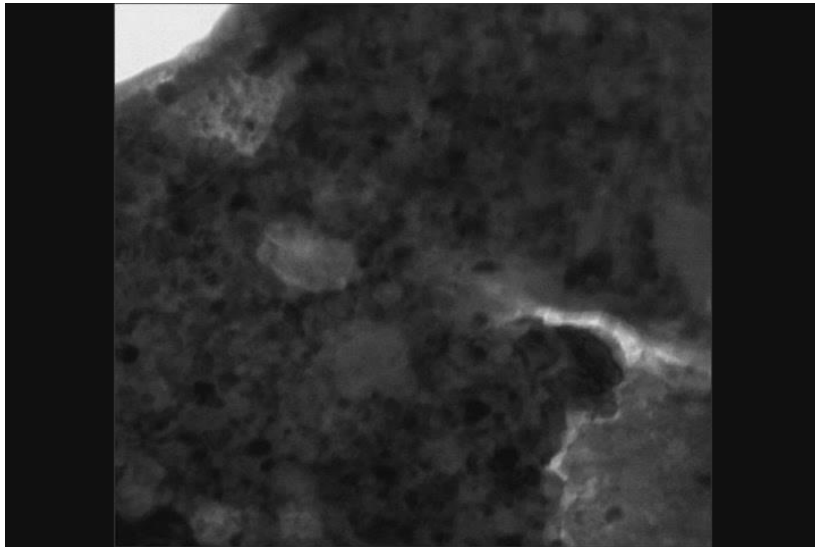
$R = 0.5$

@200Hz,



~257,000 cycles

- 256,960 total cycles before this graph starts



Acknowledgements

Anonymous Industrial Collaborators

Parts of this work were carried out in the Characterization Facility, University of Minnesota, which receives partial support from NSF through the MRSEC program.



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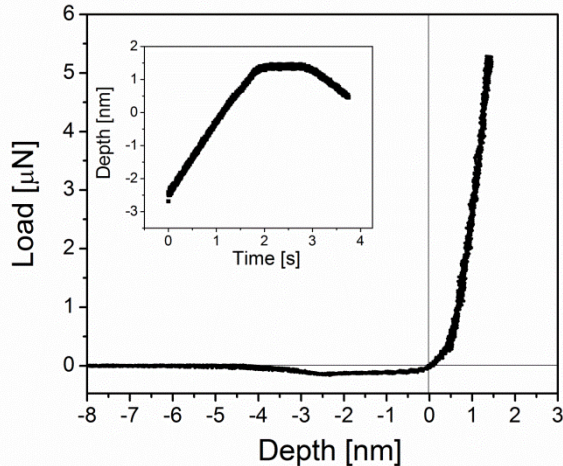


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ENERGY**

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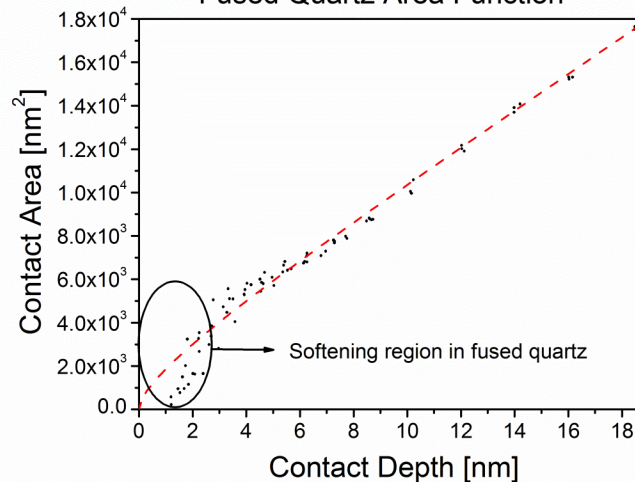
Shallow Indentation: xProbe

Single 1.4nm Indent on 3nmDLC/Glass



Approach from Air
Find positive deflection
for zero point

Fused Quartz Area Function



Density of fused quartz changes at sub 4nm contact depths, need to use high resolution tip imaging to find the tip shape for shallow indents

Convolved Image from Scan

